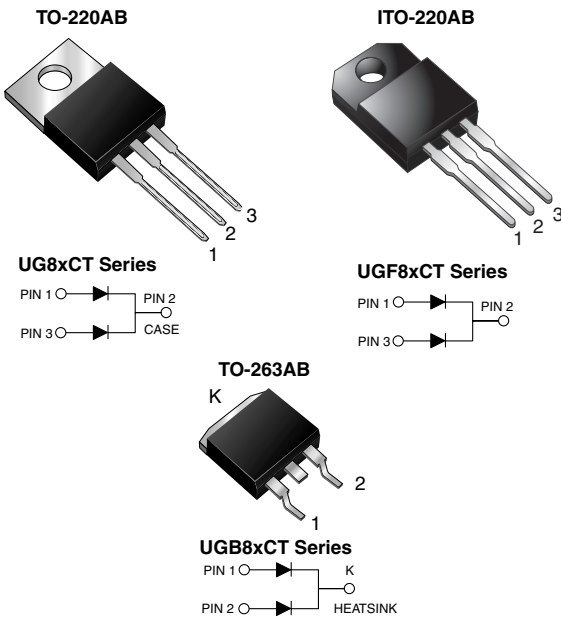


Dual Common-Cathode Ultrafast Plastic Rectifier



FEATURES

- Glass passivated chip junction
- Ultrafast recovery time
- Soft recovery characteristics
- Low switching losses, high efficiency
- High forward surge capability
- Meets MSL level 1, per J-STD-020, LF maximum peak of 245 °C (for TO-263AB package)
- Solder dip 260 °C, 40 s (for TO-220AB and ITO-220AB package)
- Component in accordance to RoHS 2002/95/EC and WEEE 2002/96/EC



RoHS
COMPLIANT

TYPICAL APPLICATIONS

For use in high voltage and high frequency power factor corrector, freewheeling diodes and secondary dc-to-dc rectification application.

MECHANICAL DATA

Case: TO-220AB, ITO-220AB, TO-263AB

Epoxy meets UL 94V-0 flammability rating

Terminals: Matte tin plated leads, solderable per J-STD-002 and JESD22-B102

E3 suffix for consumer grade, meets JESD 201 class 1A whisker test, HE3 suffix for high reliability grade (AEC Q101 qualified), meets JESD 201 class 2 whisker test

Polarity: As marked

Mounting Torque: 10 in-lbs maximum

PRIMARY CHARACTERISTICS	
$I_{F(AV)}$	4 A x 2
V_{RRM}	500 V, 600 V
I_{FSM}	65 A
t_{rr}	25 ns
V_F	1.50 V
$T_J \text{ max.}$	150 °C

MAXIMUM RATINGS ($T_C = 25\text{ °C}$ unless otherwise noted)				
PARAMETER	SYMBOL	UG8HCT	UG8JCT	UNIT
Maximum repetitive peak reverse voltage	V_{RRM}	500	600	V
Maximum working reverse voltage	V_{RWM}	400	480	V
Maximum RMS voltage	V_{RMS}	350	420	V
Maximum DC blocking voltage	V_{DC}	500	600	V
Maximum average forward rectified current	$I_{F(AV)}$	8.0		A
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load per diode	I_{FSM}	65		A
Operating junction and storage temperature range	T_J, T_{STG}	- 55 to + 150		°C
Isolation voltage (ITO-220AB only) from terminal to heatsink $t = 1$ min	V_{AC}	1500		V

ELECTRICAL CHARACTERISTICS ($T_C = 25\text{ }^\circ\text{C}$ unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	UG8HCT	UG8JCT	UNIT
Maximum instantaneous forward voltage per diode ⁽¹⁾	$I_F = 4\text{ A}$ $I_F = 4\text{ A}$	$T_J = 25\text{ }^\circ\text{C}$ $T_J = 125\text{ }^\circ\text{C}$	V_F	1.75 1.50		V
Maximum DC reverse current per diode at V_{RWM}		$T_J = 25\text{ }^\circ\text{C}$ $T_J = 100\text{ }^\circ\text{C}$ $T_J = 125\text{ }^\circ\text{C}$	I_R	30 800 4		μA μA mA
Maximum reverse recovery time per diode	$I_F = 0.5\text{ A}$, $I_R = 1.0\text{ A}$, $I_{rr} = 0.25\text{ A}$		t_{rr}	25		ns
Maximum reverse recovery time per diode	$I_F = 1.0\text{ A}$, $dl/dt = 50\text{ A}/\mu\text{s}$, $V_R = 30\text{ V}$, $I_{rr} = 0.1 I_{RM}$		t_{rr}	50		ns
Typical softness factor (t_b/t_a)	$I_F = 4.0\text{ A}$, $dl/dt = 240\text{ A}/\mu\text{s}$, $V_R = 400\text{ V}$, $I_{rr} = 0.1 I_{RM}$		S	0.9		-
Maximum reverse recovery current per diode	$I_F = 4.0\text{ A}$, $dl/dt = 32\text{ A}/\mu\text{s}$, $V_R = 400\text{ V}$, $T_C = 125\text{ }^\circ\text{C}$		I_{RM}	3.0		A
Maximum reverse recovery current per diode	$I_F = 4.0\text{ A}$, $dl/dt = 240\text{ A}/\mu\text{s}$, $V_R = 400\text{ V}$, $T_C = 125\text{ }^\circ\text{C}$		I_{RM}	8.0		A
Peak forward recovery time per diode	$I_F = 4.0\text{ A}$, $dl/dt = 64\text{ A}/\mu\text{s}$, $V_F = 1.1 V_{F\text{ max}}$		t_{fr}	500		ns

Note:(1) Pulse test: 300 μs pulse width, 1 % duty cycle

THERMAL CHARACTERISTICS ($T_C = 25\text{ }^\circ\text{C}$ unless otherwise noted)					
PARAMETER	SYMBOL	UG8	UGF8	UGB8	UNIT
Typical thermal resistance from junction to case per diode	$R_{\theta JC}$	3.5	6.0	3.5	$^\circ\text{C}/\text{W}$

ORDERING INFORMATION (Example)					
PACKAGE	PREFERRED P/N	UNIT WEIGHT (g)	PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
TO-220AB	UG8JCT-E3/45	1.85	45	50/tube	Tube
ITO-220AB	UGF8JCT-E3/45	2.00	45	50/tube	Tube
TO-263AB	UGB8JCT-E3/45	1.35	45	50/tube	Tube
TO-263AB	UGB8JCT-E3/81	1.35	81	800/reel	Tape and reel
TO-220AB	UG8JCTHE3/45 ⁽¹⁾	1.85	45	50/tube	Tube
ITO-220AB	UGF8JCTHE3/45 ⁽¹⁾	2.00	45	50/tube	Tube
TO-263AB	UGB8JCTHE3/45 ⁽¹⁾	1.35	45	50/tube	Tube
TO-263AB	UGB8JCTHE3/81 ⁽¹⁾	1.35	81	800/reel	Tape and reel

Note:

(1) Automotive grade AEC Q101 qualified



RATINGS AND CHARACTERISTICS CURVES

($T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)

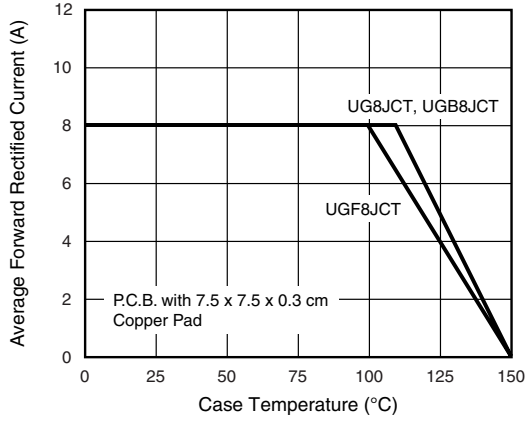


Figure 1. Maximum Forward Current Derating Curve

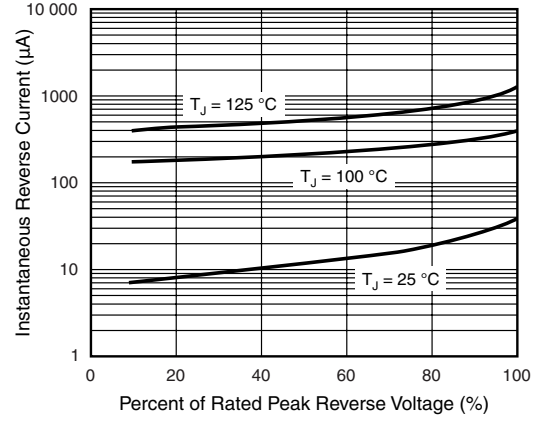


Figure 4. Typical Reverse Leakage Characteristics Per Diode

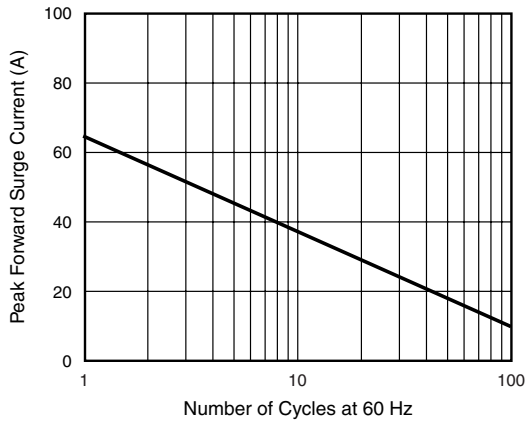


Figure 2. Maximum Non-Repetitive Peak Forward Surge Current Per Diode

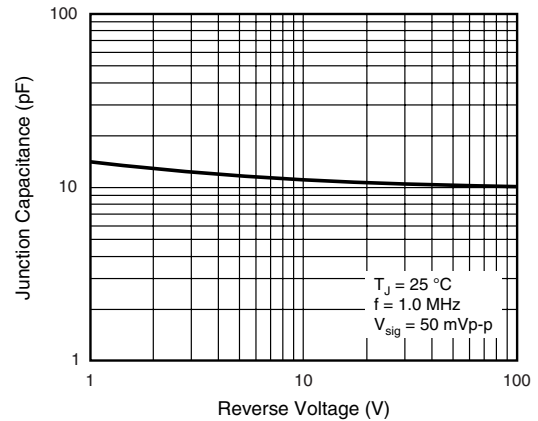


Figure 5. Typical Junction Capacitance Per Diode

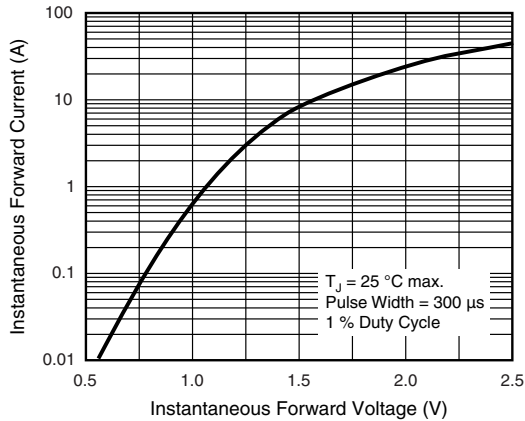


Figure 3. Typical Instantaneous Forward Characteristics Per Diode

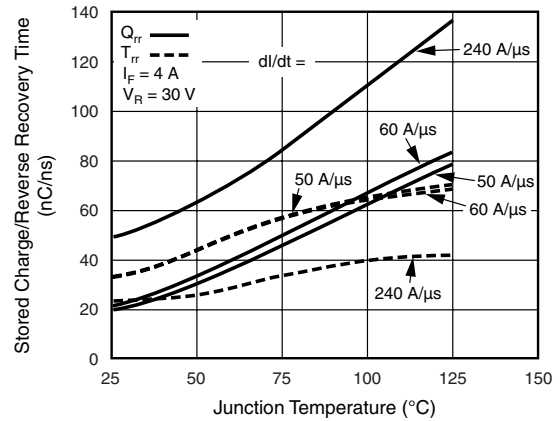


Figure 6. Reverse Switching Characteristics Per Diode

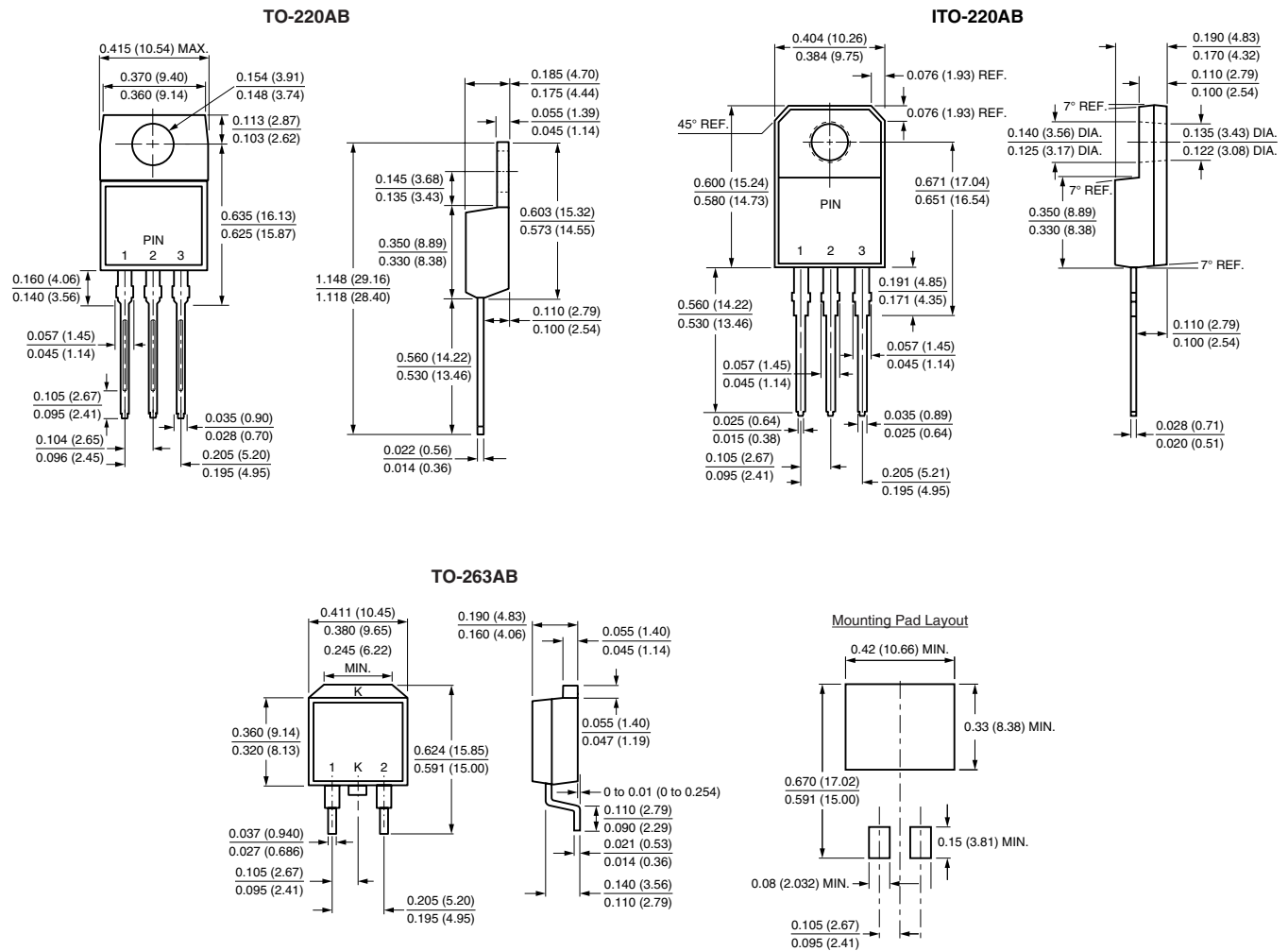
UG(F,B)8HCT & UG(F,B)8JCT

New Product

Vishay General Semiconductor



PACKAGE OUTLINE DIMENSIONS in inches (millimeters)





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